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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: Chailen et al.

Docket No.: AGLE0027

Serial No.: 09/909,774

Art Unit: 2154

Filed: July 19, 2001

Examiner: Unassigned

Title: MULTI-DIMENSIONAL INTEGRATED CIRCUIT CONNECTION NETWORK
USING LDT

INFORMATION DISCLOSURE STATEMENT

Assistant Commissioner for Patents
Washington, DC 20231

Sir:

This Information Disclosure Statement is submitted:

(X) under 37 CFR 1.97(b), or
(within three months of filing national application; or date of entry of international application; or before mailing date of first office action on the merits; whichever occurs last)

() under 37 CFR 1.97(c) together with either a:
() Certification under 37 CFR 1.97(e), or
() a \$220.00 fee under 37 CFR 1.17(p), or
(After the CFR 1.97(b) time period, but before final action or notice of allowance, whichever occurs first)

() under 37 CFR 1.97(d) together with a:
() Certification under 37 CFR 1.97(e), and
() a \$220.00 fee under 37 CFR 1.17(d)(2)(ii), and
() a \$130.00 petition fee set forth in 37 CFR 1.17(i)(1)



Filed after final action or notice of allowance, whichever occurs first, but before payment of the
(issue fee)

(X) The Commissioner is authorized to charge any additional fees or credit any overpayment to Deposit Account No. 07-1445 (Order No. AGLE0027). A copy of this sheet is enclosed for accounting purposes.

(X) Applicant(s) submit herewith Form PTO 1449 -- Information Disclosure Citation together with copies of patents, publications or other information of which applicant(s) are aware, which applicant(s) believe(s) may be material to the examination of this application and for which there may be a duty to disclose in accordance with 37 CFR 1.25.

() A concise explanation of the relevance of foreign language patents, foreign language publications and other foreign language information listed on PTO Form 1449, as presently understood by the individual(s) designated in 37 CFR 156(c) most knowledgeable about the content is given on the attached sheet, or where a foreign language patent is cited in a search report or other action by a foreign patent office in a counterpart foreign application, an English language version of the search report or action which indicates the degree of relevance found by the foreign office is listed on form PTO 1449 and is enclosed herewith.

It is requested that the information disclosed herein be made of record in this application.

Respectfully Submitted,

A handwritten signature in black ink, appearing to read "Michael Glenn".

Michael Glenn
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Customer No. 22862

Form 1449 (Modified)				Atty. Docket No. AGLE0027	Serial No.: 09/909,774
Information Disclosure Statement By Applicant				Applicant: Chaiken et al.	
(Use Several Sheets if Necessary)				Filing Date: July 19, 2001	Group: 2154 2187

U.S. Patent Documents

Examiner Initial	No.	Patent No.	Date	Patentee	Class	Sub-class	Filing Date
RIE	A	4,695,944	9/22/87	Zandveld et al.	364	200	9/22/86
RIE	B	4,723,238	2/2/88	Israel et al.	370	60	3/24/86
RIE	C	4,821,265	4/11/89	Albal et al.	370	110.1	4/6/87
RIE	D	4,903,258	2/20/90	Kuhlmann et al.	370	58.2	8/19/88
RIE	E	4,907,225	3/6/90	Gulick et al.	370	94.1	6/16/89
RIE	F	4,939,728	7/3/90	Markkula, Jr. et al.	370	94.3	12/19/88
RIE	G	4,949,338	8/14/90	Albal et al.	370	85.6	11/14/88
RIE	H	4,955,018	9/4/90	Twitty et al.	370	85.1	11/8/88
RIE	I	4,962,497	10/9/90	Ferenc et al.	370	60.1	9/21/89
RIE	J	4,984,237	1/8/91	Franaszek	370	60	6/29/89
RIE	K	4,993,017	2/12/91	Bachinger et al.	370	58.2	2/22/89
RIE	L	5,093,827	3/3/92	Franklin et al.	370	60.1	9/21/89
RIE	M	5,124,978	6/23/92	Chao	370	60	1/3/91
RIE	N	5,130,984	7/14/92	Cisneros	370	94.1	152/18/90
RIE	O	5,157,654	10/20/92	Cisneros	370	60	12/18/90
RIE	P	5,179,552	1/12/93	Chao	370	60	1/10/92
RIE	Q	5,208,650	3/27/01	Hassell et al.	370	392	4/2/98
RIE	R	5,408,609	4/18/95	Malgogne et al.	395	200	12/19/91
RIE	S	5,630,061	5/13/97	Richter et al.	395	200.02	4/19/93
RIE	T	5,719,860	2/17/98	Maison et al.	370	347	3/22/96
RIE	U	5,793,770	8/11/98	St. John et al.	370	401	11/18/96
RIE	V	5,844,888	12/1/98	Markkula, Jr. et al.	370	255	6/7/95
RIE	W	5,894,474	4/13/99	Maison et al.	370	347	12/20/97
RIE	X	6,015,300	1/18/00	Schmidt, Jr. et al.	439	61	8/28/97
RIE	Y	6,091,729	7/18/00	Dove	370	395	11/26/97
RIE	Z	6,141,691	10/31/00	Frink et al.	709	233	4/3/98

Foreign Patent or Published Foreign Patent Application

Examiner Initial	No.	Document No.	Publication Date	Country or Patent Office	Class	Sub-class	Translation	
							Yes	No
RIE	a	0621713	26/10/94	EPO	29	06		X
RIE	b	0285330	05/10/8	EPO	11	04		X

Ex. R. Elmoe

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Other Documents

Examiner Initial	No.	Author, Title, Date, Place (e.g. Journal) of Publication
RIE	c	AMD Discloses New Technologies at Microprocessor Forum; October 5, 1999; AMD – News Release #99105; http://www.amd.com/news/prodpr/99105.html ; Printout from INSPEC.
RIE	d	HyperTransport " Technology Frequently Asked Questions; http://www1.amd.com/products/cpg/showall/1,1395,,00.html?type=HyperTransport ; Printout from INSPEC.
RIE	e	Jayant Matthew; API NetWorks Introduces the First HyerTransport-to-PCI Bridge Chip; Electronic News; April 2, 2001; Print out from INSPEC.
RIE	f	Darrell Dunn; API Revving Up Hypertransport Bus - - Looks to raise interest in the technology via chip that links it to PCI; EBN; April 2, 2001; Print out from INSPEC.
RIE	g	Jerry Ascierto; Rival post-PCI plans spark talk of bus war; Electronic Engineering Times; April 2, 2001; Print out from INSPEC.
RIE	h	Ken Popovich; Intel puts bus plan in gear – Chip maker challenges AMD's HyperTransport Architecture in bid to replace PCI in PC's, servers; eWeek; March 12, 2001; INPEC printout.
RIE	i	Ken Popovich; HyperTransport speeds data transfer (Advanced Micro Devices Inc.); eWeek; February 26, 2001; print out from INSPEC.
RIE	j	Jayant Matthew; AMD Unveils Speedy Chip-to-Chip Link; Electronic News; February 19, 2001; Print out from INPSEC.
RIE	k	Linley Gwennap; AMD strikes Lightening; Electronic Engineering Times; February 19, 2001; print out from INSPEC.
RIE	l	Jerry Ascierto; Rival post-PCI plans spark talk of bus war; Electronic Engineering Times; 2001, n 1160, April 2, 2001; print out from INSPEC.
RIE	m	Dave Polifko ; The Optical Internet: Taking Up Where SONET Leaves Off; Telecommunications; June 2000; print out from INSPEC.
RIE	n	Chu-Sun Yen, Richard C. Walker, Patrick T. Petruno; Cheryl Stout; Benny W.H. Lai; and William J. McFarland; G-Link: A chipset for gigabit-rate data communication; Hewlett-Packard Journal; October 1992; print out from INSPEC.
RIE	o	Mark Miller; Which route for routers?; Buyer's Guide, As vendors relocate the function of routers, look for those devices to take on many new faces; Network World; august 28, 1995; INSPEC print out.

Examiner: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

Ex. R. Eunmore

6/14/2003